

PCB Specifications: Size:

- 189.0x55.0 mm

Class: 8C

Track width: ≥ 0.2 mm

Insulation distance: ≥ 0.2 mm

Minimum drill size: ≥ 0.4 mm (finished metalized hole: 0.3 mm)

Minimum slot width: \geq N/A mm

Ring collar: ≥ 0.1 mm

Stackup:

Name	Type	Color	Thickness	Material	Epsilon	Loss tangent
F.SilkS	Top Silk Screen					
F.Paste	Top Solder Paste					
F.Mask	Top Solder Mask		10			
F.Cu	copper		35			
dielectric 1	prepreg		100	FR4	4.5	0.020
In1.Cu	copper		35			
dielectric 2	core		1240	FR4	4.5	0.020
In2.Cu	copper		35			
dielectric 3	prepreg		100	FR4	4.5	0.020
B.Cu	copper		35			
B.Mask	Bottom Solder Mask		10			
B.Paste	Bottom Solder Paste					
B.SilkS	Bottom Silk Screen					

Materials:

- FR4, 1.6 mm
- None
- 4 layers
- 35 μ m copper thickness

Solder mask:

- TOP / BOTTOM
- Green

Marking:

- TOP / BOTTOM screen printing
- Silk: White

Other markings:

- ROHS / UL / Date - Yes if available